

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	49	((IC OR "integrated circuit" OR chip) WITH ink\$3 WITH mark\$3 WITH (stamp\$3 OR roller OR contact\$3)) SAME (ink WITH (cure OR cured OR curing))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/08 06:32
L3	51	(IC OR "integrated circuit" OR chip) WITH ink\$3 WITH mark\$3 WITH (stamp\$3 OR roller OR contact\$3) AND (ink WITH (cure OR cured OR curing))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/08 07:25
L4	4276	(257/666).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/08 07:25
S1	2	((("5977624") or ("6004867")).PN.	USPAT	OR	OFF	2006/08/16 15:36
S2	860	semi\$2conductor AND (ink NEAR mark\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/07 16:09
S3	4	("4390885" "4568879" "4992729").PN. OR ("6049203").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/03 16:53
S4	4	("4568879" "4992729" "5455605" "6049203").PN. OR ("6702489").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/03 16:54
S5	6	("3340541" "3943527").PN. OR ("5455605").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/03 16:56
S6	30	("2766484" "3345567" "3614940" "3884183" "3895748" "3900866").PN. OR ("3943527").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/03 16:57

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S8	29	(US-20050285278-\$ or US-20050224791-\$ or US-20050167833-\$ or US-20050280665-\$ or US-20050261863-\$ or US-20040173888-\$ or US-20050164416-\$ or US-20040209397-\$ or US-20020177875-\$ or US-20040030517-\$ or US-20030166313-\$ or US-20030077418-\$).did. or (US-6939501-\$ or US-6702489-\$ or US-6565670-\$ or US-6539960-\$ or US-6535004-\$ or US-6049203-\$ or US-5997388-\$ or US-5994715-\$ or US-6018686-\$ or US-5455605-\$ or US-4928587-\$ or US-5359203-\$). did. or (US-3345567-\$).did. or (JP-2004079830-\$ or JP-2003057294-\$ or JP-62169644-\$).did. or (JP-2004079830-\$).did.	US-PGPUB; USPAT; USOCR; JPO; DERWENT	OR	ON	2006/03/03 17:04
S9	64	S3 OR S4 OR S5 OR S6 OR S7 OR S8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/03 17:04
S10	1	"804146".ap.	US-PGPUB	OR	ON	2006/03/06 09:17
S11	5797	((257/698,797,798) or (438/401, 462,975,200)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/06 10:53
S12	1	"20030157762"	US-PGPUB	OR	ON	2006/03/06 11:45
S13	1924	position\$4 SAME print\$4 SAME oppos\$4 SAME coaxial\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/06 11:52
S14	513	(position\$4 SAME print\$4 SAME oppos\$4 SAME coaxial\$3) AND ink	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/06 11:53

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S15	78	(position\$4 SAME print\$4 SAME oppos\$4 SAME coaxial\$3) AND (semi\$2conductor OR wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/06 11:53
S16	1	"20040060910"	US-PGPUB	OR	ON	2006/03/06 12:06
S17	2	((("6187615") or ("6287893"))).PN.	USPAT	OR	OFF	2006/08/16 15:48
S18	12	"5962919"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 15:48
S19	2	("6744144").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/17 08:59
S20	14	("20020076897" "20020168832" "4214249" "4401992" "5061341" "5984190" "5985377" "6162651" "6175162" "6181017" "6337122" "6432796" "6524881").PN. OR ("6744144").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/17 08:59
S21	39	("4375025" "4585931" "4638144" "4707722" "4753863" "4861620" "4945204" "5278442" "5329090" "5357077" "5985510" "6153034").PN. OR ("6337122").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/17 09:08
S22	223	ink AND semiconductor AND (print\$3 OR mark\$3) WITH (die OR package OR dice OR wafer OR semiconductor) WITH ("one action" OR "single step" OR simultaneously OR "at the same time" OR together)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 11:19
S23	5368	(ink\$3 OR print\$3 OR mark\$3) WITH (die OR package OR dice OR wafer OR semiconductor) WITH ("one action" OR "single step" OR simultaneously OR "at the same time" OR together)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 11:26

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S24	1114	S23 AND ("257" OR "438").clas.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 10:52
S25	1032	S24 NOT S22	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 11:00
S26	24	(ink NEAR marking).ab. AND ("257" OR "438").clas.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 11:00
S27	6	("4570058").PN. OR ("4928002").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/17 11:03
S28	231	ink AND semiconductor AND (print\$3 OR mark\$3) WITH (die OR package OR dice OR wafer OR semiconductor) WITH ("one action" OR "one step" OR "single step" OR simultaneously OR "at the same time" OR together)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 11:21
S29	8	S28 NOT S22	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 11:22
S30	161	(ink WITH print\$3) SAME ("single step")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 11:23
S31	24	S30 AND package	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 11:25

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S32	6023	((257/698,797,798) or (438/401, 462,975,200)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/17 11:27
S33	1493	S32 AND ("one action" OR "single step" OR simultaneously OR "at the same time")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 11:27
S34	283	S32 AND (print\$3 OR mark\$3) WITH ("one action" OR "single step" OR simultaneously OR "at the same time")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 11:29
S35	284	S32 AND (print\$3 OR mark\$3) WITH ("one action" OR "single step" OR simultaneously OR "at the same time" OR synchronous)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 11:29
S36	284	S32 AND (print\$3 OR mark\$3) WITH ("one action" OR "single step" OR simultaneously OR "at the same time" OR synchronous\$2)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 13:13
S37	1	S36 NOT S34	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 11:29
S38	2	("6337122").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/17 13:13
S40	1243	semi\$2conductor AND (ink NEAR (mark\$4 OR print\$3)) AND ("257" OR "438").clas.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/07 16:29

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S41	179	S40 AND (cur\$3 WITH ink\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/07 16:13
S42	26	("3751587" "4148057" "4375025" "4585931" "4638144" "4707722" "4719502" "4753863" "4861620" "4945204" "5030551" "5157412" "5206280" "5262470" "5329090" "5346802" "5357077" "5373039" "5413629" "5445923").PN. OR ("6113992"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/01/07 16:17
S43	114	(semi\$2conductor OR wafer) AND (ink NEAR (mark\$4 OR print\$3)) AND ((mark\$3 OR print\$3) WITH (device OR head OR nozzle) WITH (contact\$3 OR touch\$3)) AND (cur\$3 WITH after WITH (print\$3 OR mark\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/07 16:37
S44	23	(semi\$2conductor OR wafer) AND (ink NEAR (mark\$4 OR print\$3)) AND ((mark\$3 OR print\$3) WITH (device OR head OR nozzle) WITH (contact\$3 OR touch\$3)) AND ((cure OR cured OR curing) WITH after WITH (print\$3 OR mark\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/07 16:38
S45	48	(semi\$2conductor OR wafer) AND (ink\$3 WITH (mark\$4 OR print\$3)) AND ((mark\$3 OR print\$3) WITH (device OR head OR nozzle) WITH (contact\$3 OR touch\$3)) AND ((cure OR cured OR curing) WITH after WITH (print\$3 OR mark\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/07 16:42
S46	9	(stamp\$3 WITH ink WITH (side OR surface) WITH (die OR package)) AND ("257" OR "438").clas.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/07 16:53
S47	9	(die WITH (mark\$3 OR print\$3) WITH ink\$3) SAME ((next OR after) WITH ink WITH (cured OR curing OR cure))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/07 17:02

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S48	0	((die OR wafer) WITH (mark\$3 OR print\$3) WITH inker) AND ((cure OR curing OR cured) WITH ink)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/07 17:04
S49	237	((die OR wafer) WITH (mark\$3 OR print\$3) WITH ink\$3) AND ((cure OR curing OR cured) WITH ink\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/07 17:04
S50	152	((die OR wafer) WITH (mark\$3 OR print\$3) WITH ink\$3) AND ((cure OR curing OR cured) WITH ink\$3) AND (mark\$3 OR print\$3).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/07 18:06
S51	507	((die OR wafer) WITH (mark\$3 OR print\$3) WITH (device OR head) WITH contact\$3) AND (wafer OR semi\$1conductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/07 18:09
S52	3	((die OR wafer) WITH (mark\$3 OR print\$3) WITH (device OR head) WITH contact\$3) AND (wafer OR semi\$1conductor) AND (ink\$3 WITH (cure OR cured OR curing))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/07 18:33
S53	5	6-120281 OR "6120281"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/07 18:34
S54	12	("3534440" "4519972" "4944908" "5388803" "5817208").PN. OR ("6270712").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/01/07 18:35